Cost-Effective Eco-Friendly ENIG Solution Delivers Improved Reliability

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liloTree has developed an eco-friendly solution to address ENIG-related black pad failures and brittle solder joints. ENIG-Premium™, liloTree’s proprietary technology, involves nano-level engineering that resolves root causes of failures associated with conventional ENIG.

ENIG-Premium™ was initiated when liloTree sought to find solutions to several field failures where black pads and brittle failures at solder joints were related to the current offerings of ENIG. “Development of ENIG-Premium™ sprouted from actual customer pain points,” said Kunal Shah, chief scientist at liloTree. “More than 40 PCB manufacturers and OEMs with whom we consulted indicated that they had faced ENIG-related issues in the past, and the frequency seemed to be high.”

The development of ENIG-Premium™ was fueled by a Small Business Innovation Research (SBIR) grant from the National Science Foundation. This eco-friendly solution is now available in the market. The response has been positive, and several of the leading OEM/PCB manufacturers are currently testing/qualifying/adopting ENIG-Premium™ and realizing the benefits of improved reliability of electronic assemblies.

For more information:
http://www.lilotree.com/home

About liloTree
liloTree develops, manufactures, and distributes advanced engineered materials including ENIG-Premium™ and other product improvement solutions for industries such as aviation & aerospace, medical electronics, semiconductor, naval electronics, consumer electronics, etc. Headquartered in Woodinville, Washington, liloTree offers materials and solutions worldwide.